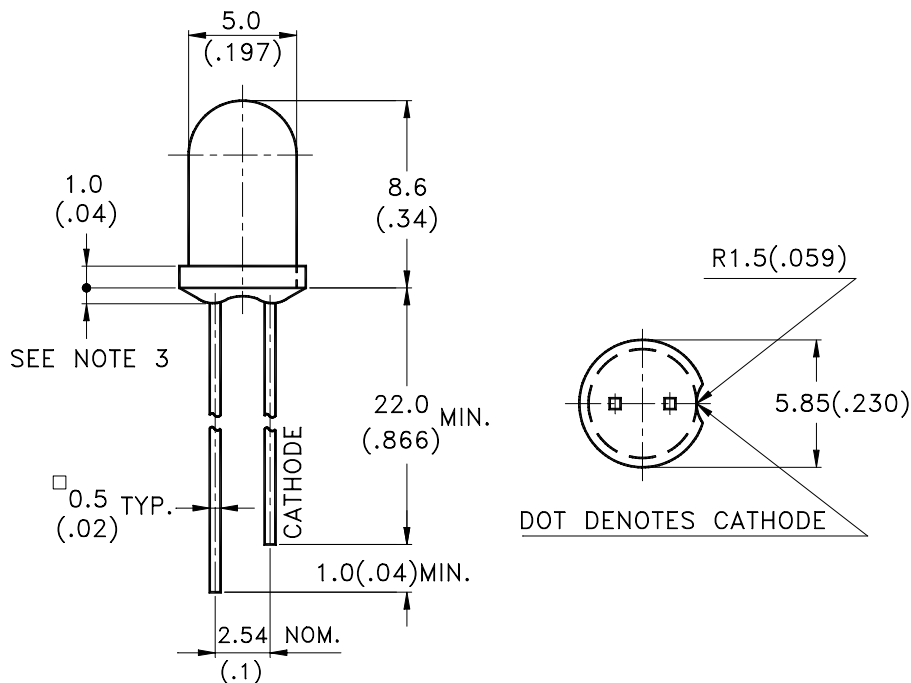


Features

- * High Intensity.
- * Popular T-1 3/4 diameter Package.
- * Selected minimum intensities.
- * Wide viewing Angle.
- * General purpose leads.
- * Reliable and rugged.

Package Dimensions



Part No.	Lens	Source Color
LTL-307EE	Red Transparent	Hi.Eff.Red

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25\text{mm} (.010\text{'})$ unless otherwise noted.
3. Protruded resin under flange is 1.0mm(.04") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.



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Absolute Maximum Ratings at TA=25

Parameter	Maximum Rating	Unit
Power Dissipation	100	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	90	mA
Continuous Forward Current	30	mA
Derating Linear From 50	0.4	mA/
Reverse Voltage	5	V
Operating Temperature Range	-55 to + 100	
Storage Temperature Range	-55 to + 100	
Lead Soldering Temperature [1.6mm(.063") From Body]	260 for 5 Seconds	



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Electrical / Optical Characteristics at TA=25

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	29	90		mcd	I _F = 10mA Note 1,4
Viewing Angle	2 1/2		40		deg	Note 2 (Fig.6)
Peak Emission Wavelength	λ _p		635		nm	Measurement @Peak (Fig.1)
Dominant Wavelength	λ _d	615	625	632	nm	Note 3
Spectral Line Half-Width			40		nm	
Forward Voltage	V _F		2.0	2.6	V	I _F = 20mA
Reverse Current	I _R			100	μ A	V _R = 5V
Capacitance	C		20		pF	V _F = 0 , f = 1MHz

- Note: 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclairage) eye-response curve.
2. 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. The dominant wavelength, λ_d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
4. The I_v guarantee should be added ±15% .

Typical Electrical / Optical Characteristics Curves

(25 Ambient Temperature Unless Otherwise Noted)

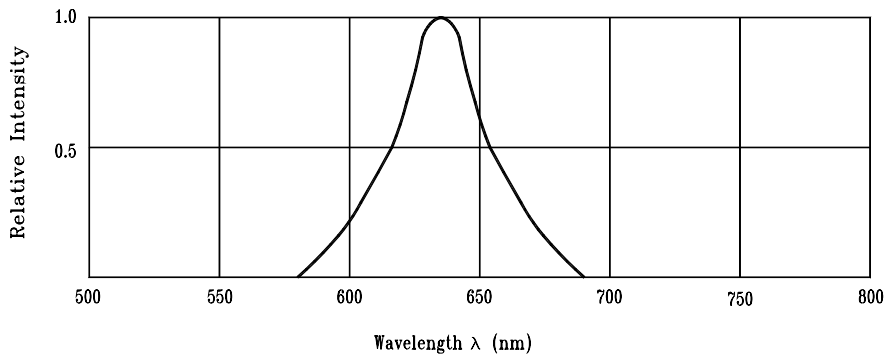


Fig.1 Relative Intensity vs. Wavelength

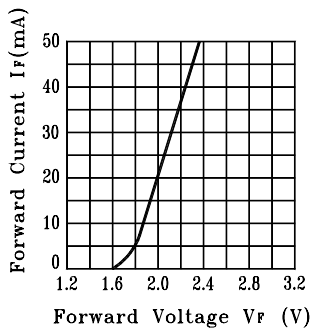


Fig.2 Forward Current vs. Forward Voltage

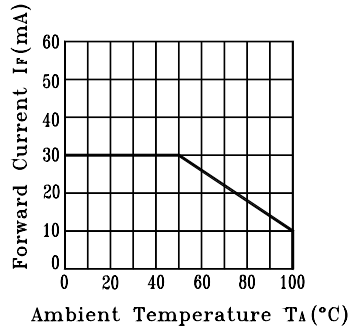


Fig.3 Forward Current Derating Curve

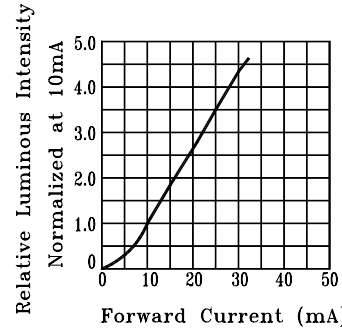


Fig.4 Relative Luminous Intensity vs. Forward Current

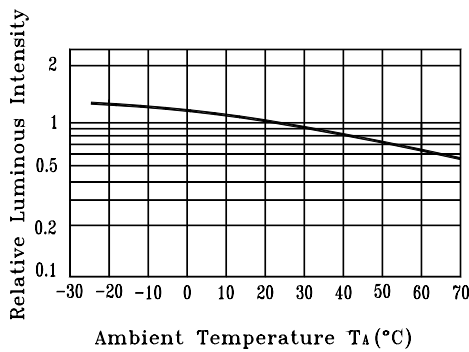


Fig.5 Luminous Intensity vs. Ambient Temperature

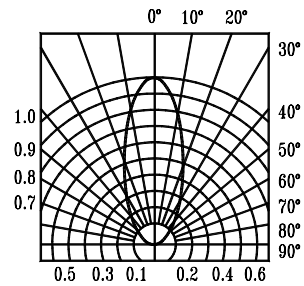


Fig.6 Spatial Distribution



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CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary.

4. Lead Forming & Assembly

During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens.

Do not use the base of the leadframe as a fulcrum during forming.

Lead forming must be done before soldering, at normal temperature.

During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical stress.

5. Soldering

When soldering, leave a minimum of 2mm clearance from the base of the lens to the soldering point.

Dipping the lens into the solder must be avoided.

Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

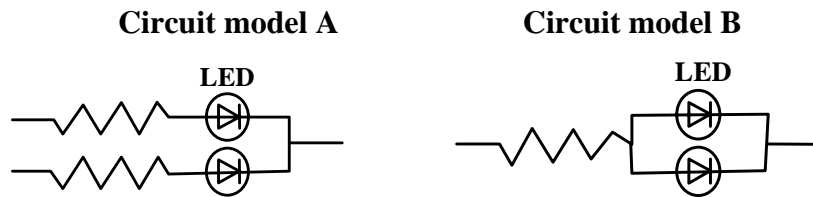
Recommended soldering conditions :

Soldering iron		Wave soldering	
Temperature	300°C Max.	Pre-heat	100°C Max.
Soldering time	3 sec. Max. (one time only)	Pre-heat time	60 sec. Max.
		Solder wave	260°C Max.
		Soldering time	10 sec. Max.

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED. IR reflow is not suitable process for through hole type LED lamp product.

6. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



(A) Recommended circuit

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs

7. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use a conductive wrist band or anti- electrostatic glove when handling these LEDs
- All devices, equipment, and machinery must be properly grounded
- Work tables, storage racks, etc. should be properly grounded
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or “no light up” at low currents. To verify for ESD damage, check for “light up” and V_f of the suspect LEDs at low currents.

The V_f of “good” LEDs should be $>2.0V@0.1mA$ for InGaN product and $>1.4V@0.1mA$ for AlInGaP product.

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